CONDUCTIVE PASTE AND GLASS CIRCUIT STRUCTURE

ABSTRACT OF THE DISCLOSURE

Provided is a conductive paste capable of adjusting resistivity and forming a conductor film having high strength of bonding with a glass substrate and high mounting strength of a metal terminal. The conductive paste contains a conductive component, a glass frit having a composition containing a Bi_2O_3-B_2O_3-SiO_2-Al_2O_3 or Bi_2O_3-B_2O_3-SiO_2-Al_2O_3-ZnO primary component and about 0.5 to 5% by weight of NiO as a secondary component, and an organic vehicle. The conductive paste is applied on a glass substrate and then baked to form a conductor film. A glass circuit structure formed by using the conductor film can be advantageously used as a defogging glass for an automobile window.